

→ ThinkSystem SR530 technical specifications

Product technical specifications

Technical specifications

The table shows SR530 detailed specifications.

SR530	Descriptions
Processor	Next-generation Intel® Xeon® processor product family (Skylake)
	Up to 125 W (Platinum, Gold, Sliver, Bronze)
Memory	Six channels per CPU
	12x DDR4 (RDIMM/LRDIMM) 2666 MHz DIMMs
	 Supports 8 GB / 16 GB / 32 GB / 64 GB DIMMs
	Up to 768 GB
Drive bay	Up to four 3.5-inch simple-swap and hot-swap support
	Up to eight 2.5-inch hot-swap support
	Up to eight 2.5-inch no backplane chassis
	Up to two M.2 internal (dual M.2 with mirroring)
RAID and storage HBA	Intel Software RAID
	RAID Controllers with eight ports
	Non-RAID HBA with eight or 16 (external only) ports

SR530	Descriptions
Networking	Embedded 2x 1GbE
	Embedded selectable LOM module up to ports
	ML2 is available
	1GbE dedicated management port
PCle	Up to three PCle 3.0 slots
Power supply	 550 W/750 W Platinum; 240 V HVDC Re
	750 W Titanium
	Energy Star 2.1 Compliance
System management	 Lenovo XClarity System Management Administrator / Pro / Integrators Controller Standard/Advanced/Enterprise Energy Manager Provisioning Manager Essentials
Thermal and cooling	 ASHRAE A4 with limitations Non-hot-swappable redundant fans